

Global Leading Company  
with World's Best Technology

# LEENO



# DISCLAIMER

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All Information about our company's financial outcome in this material were written by Korean International Financial Reporting Standards.

In addition, This material includes information about the future predictions which can be affected by known or unknown risks and uncertainties.

**The Future business prospect is supposed to be check. Because, Many such factors such as market situation and business strategy will be important in determining our future results.**

Up-to-date our company information is notified in our website. (<https://leeno.com>)

Feel free to contact us with any further questions

**Leeno Industrial Inc**

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- 01. About 'LEENO'
- 02. Competitiveness
- 03. Major Clients

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## II. Our Products

- 01. LEENO PIN
- 02. IC TEST Socket
- 03. Probe Head(Card)
- 04. Secondary Battery Test Pin
- 05. Ultrasonic Wave Probe Component

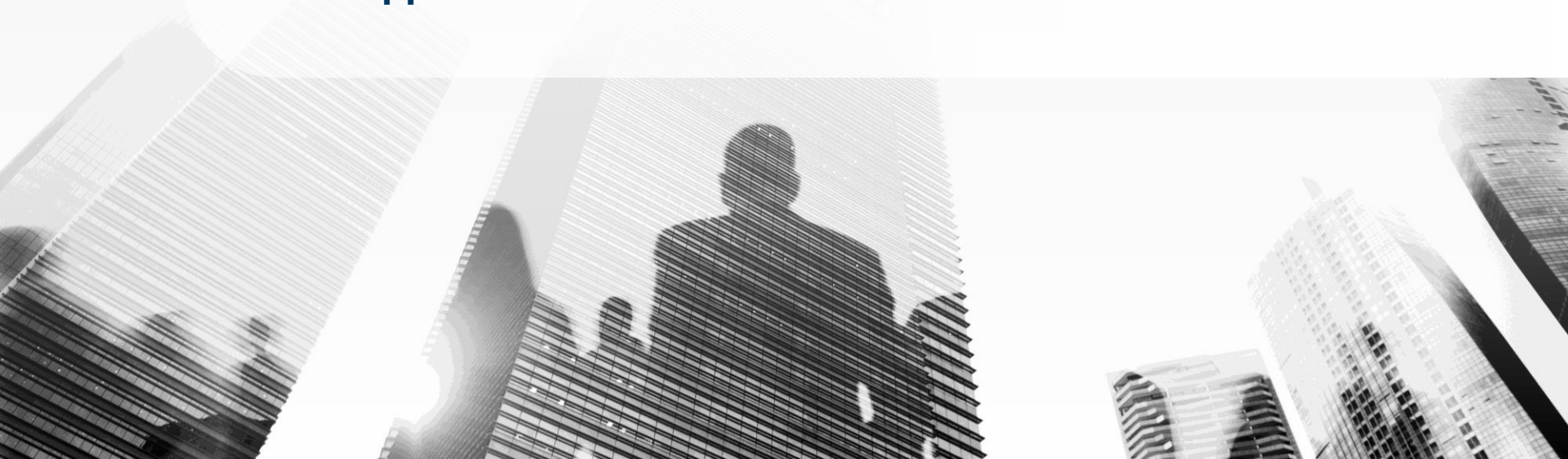
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# About 'LEENO'

## LEENO

Company Name	Leeno Industrial Inc.
CEO	Chae-Yoon, Lee
Foundation	NOV 1978 (Incorporated in DEC 1996)
Business Category	Manufacture Semiconductor Test Probe and Socket
Capital Stock	(KRW) 7.62 Billion won ('23)   (KRW) 7.62 Billion won ('24.3Q)
Revenue	(KRW) 255.6 Billion won ('23)   (KRW) 194.8 Billion won ('24.3Q)
Number of Employees	639 persons ('23)   634 persons ('24.3Q)
Head Office Location	10, MIEUMSANDAN-RO 105BEON-GIL, GANGSEO-GU, BUSAN, KOREA
Homepage	<a href="https://leeno.com">https://leeno.com</a>

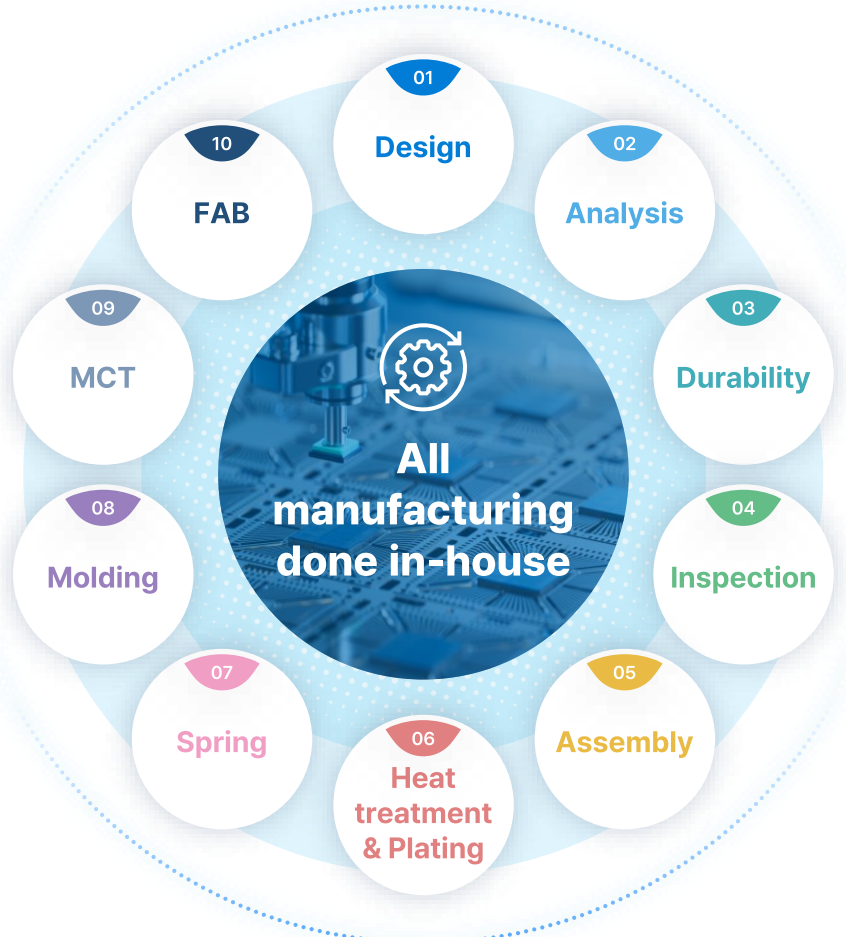


## MAIN HISTORY

- 2001. 12. Listed on KOSDAQ(058470)
- 2003. 10. Appointed "Prospective Exporter, Small&Medium Business"
- 2004. 12. Certified by DAS for ISO 9001  
11. Received an award from Korean prime minister for excellence in regional innovation
- 2005. 9. Appointed "Excellent Business" and awarded Korea Productivity Award  
11. Awarded "10 Million Dollar Export Achievement Award"
- 2006. 11. Certified by DAS for ISO 14001
- 2007. 1. Appointed "Technology Innovative Small and Medium Enterprise"  
7. Awarded "Grand Prize of Small and Medium Business people In Busan"
- 2010. 1. Concluding a contract to supply the probe for supersonic to Siemens  
11. Awarded "20 Million Dollar Export Achievement Award"
- 2012. 1. Certified ISO13485
- 2013. 5. Voted World Class 300  
6. Bonus Issue  
8. Moved in to New extend Head office  
12. Awarded "30 Million Dollar Export Achievement Award"
- 2014. 3. Awarded "Tin Tower Order of Industrial Service Merit"
- 2016. 3. Awarded Citation in 'Taxpayer day'  
12. Awarded "50 Million Dollar Export Achievement Award"
- 2017. 12. Awarded "70 Million Dollar Export Achievement Award"
- 2020. 2. Completed "NOKSAN Factory" for Medical and Plating part.
- 2021. 12. Awarded "100 Million Dollar Export Achievement Award"
- 2022. 12. Awarded "200 Million Dollar Export Achievement Award"
- 2023. 12. Certified ISO45001

# Competitiveness

## World Class Manufacturing



## Consistent, Quality Products

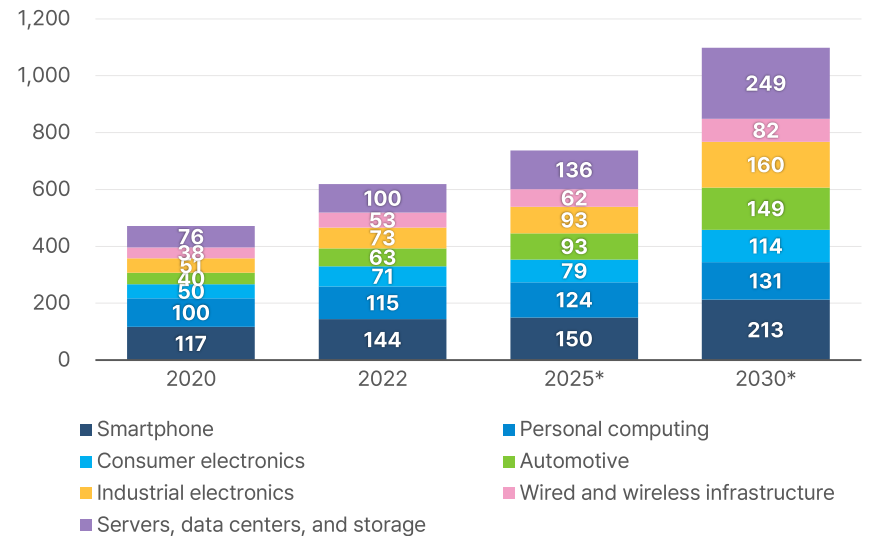


# Major Clients



## » Semiconductor market size worldwide from 2020 to 2030, by application

(units : billion U.S. dollars) Source : Statista(Feb, 2023)



Semiconductor market size worldwide by application will total 1,098 billion dollars in 2030, according to Statista. In addition, smartphone(213 billion dollars), Servers & data centers & storage(249 billion dollars), Personal computing(131 billion dollars), Automotive(149 billion dollars), Industrial electronics(160 billion dollars), Consumer electronics(114 billion dollars) and Wired & wireless infrastructure(82 billion dollars) is expected to growth in 2030.

According to Current Trend and The Fourth Industrial Revolution(such as IoT, AI, 5G, VR, AR, Big-data, Metaverse, Automatic Driving & Electronic Car), As types and functions of non-memory and memory semiconductors go into The Devices is diversifying, Demands for functions and characteristics in Semiconductor testing market is increasing. LEENO will be accompanied by the growth of the new IT market, to actively participate in the needs of the semiconductor test market with LEENO PIN and IC TEST SOCKET.

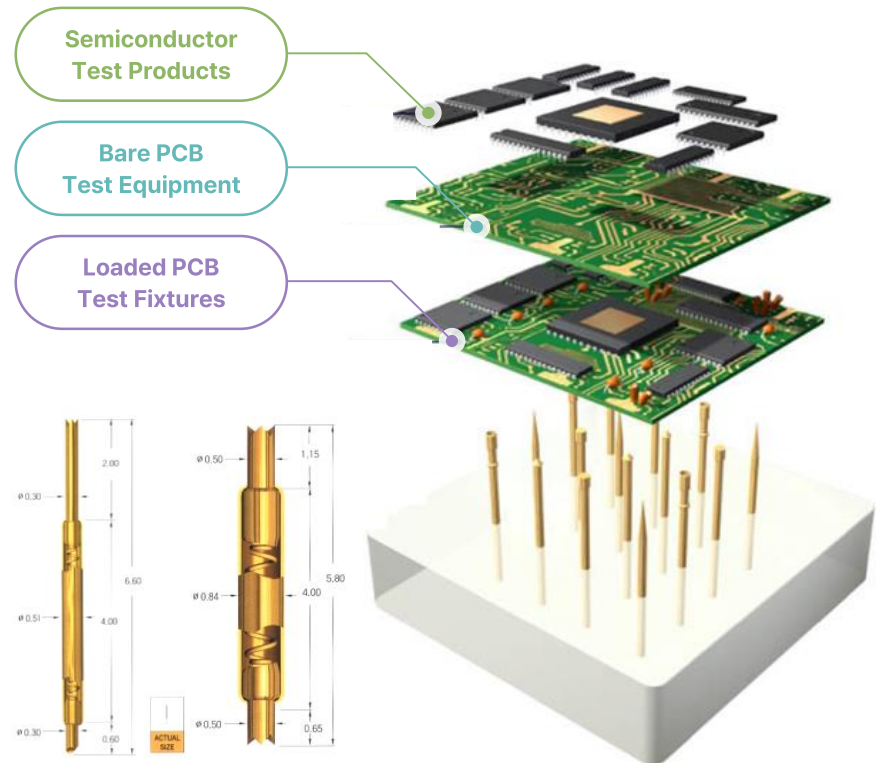
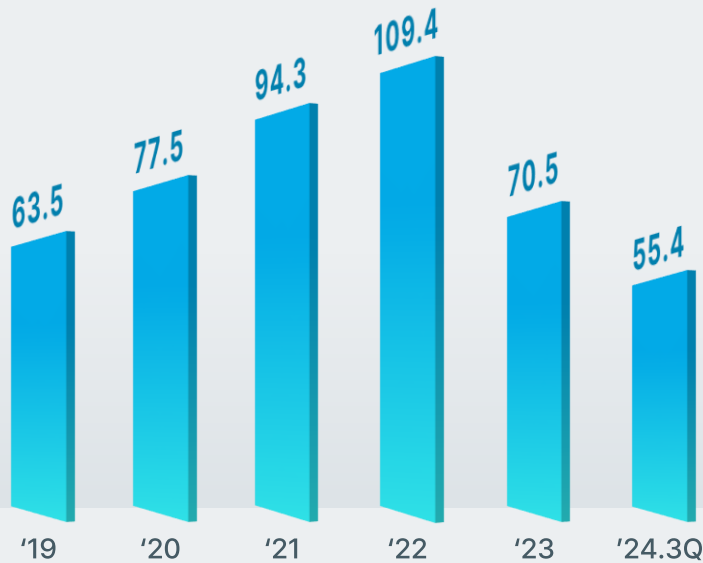
# LEENO PIN

- ☑ Contact with **electronic equipment** and **PCB circuit** to check whether properly to make or not
- ☑ LEENO PIN is our own-brand as test probe pin, and about **990 companies**(Based on sales of 2023) **are using 'LEENO PIN'**
- ☑ Recently, Along with high demand of Fine Pitch Probe with variety of electronic equipment, we are satisfied our customer's needs providing **high quality and competitive pricing**.

## Sales amount

(UNIT : KRW bil)

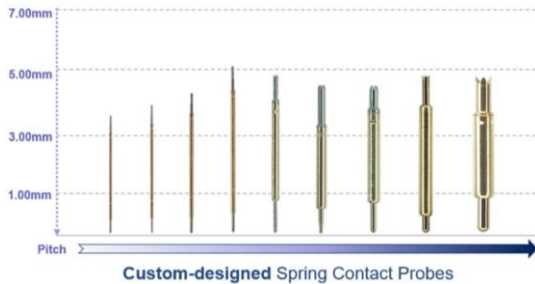
LEENO PIN(with goods and secondary battery test pin)



# LEENO PIN

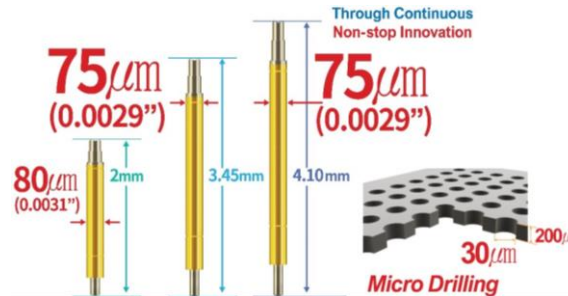
## Spring Contact Probe

LEENO possesses the capability to offer custom-designed spring contact probes, manufactured 100% in-house process with the shortest lead time possible.



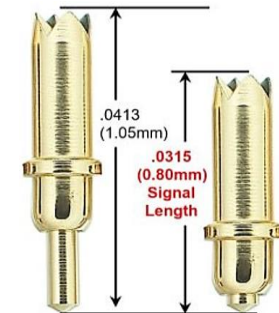
## Fine Pitch Probe

Thinnest & Shortest Fine Pitch Spring Contact Probes specifically designed for Wafer Level (RF) testing purpose.



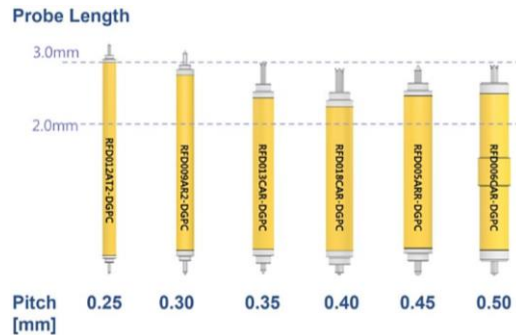
## 0.80mm Probe

Shortest Spring Contact Probe specifically designed for High Speed testing purpose.



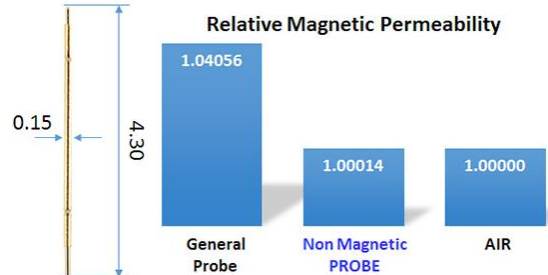
## Coaxial Probe

LEENO has successfully developed Coaxial Structured Spring Contact Probes that can be applied to Non-coaxial socket housings.



## Non Magnetic Probe

Leeno has successfully developed fine-pitch non-magnetic springs used in proximity switches, position/current sensing, and speed detection in various fields such as mobile, automotive, and industrial applications. Using its precision technology, LEENO offers customized non-magnetic probes that can be used for testing navigation devices.



## ICT Probe

LEENO provides a wide variety of choices for ICT probes, offering over 1,000 standard models, as well as custom-designed ICT probes specially made to the customer's specifications





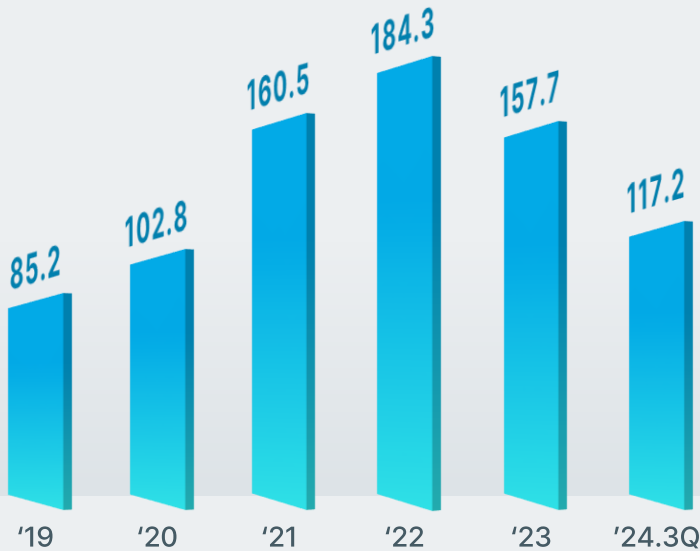
# IC TEST SOCKET

- ☑ IC Test socket **has been used to test memory and non-memory IC semiconductor**. The purpose of this is to test electrical signal after contacting package which is located in test socket.
- ☑ Our **innovative vertical type in IC test socket** has been commercialized for 20 years through out developing innovative technology

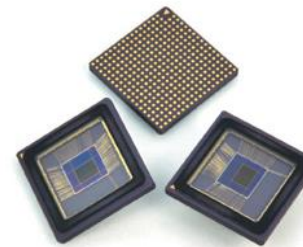
## Sales amount

(UNIT : KRW bil)

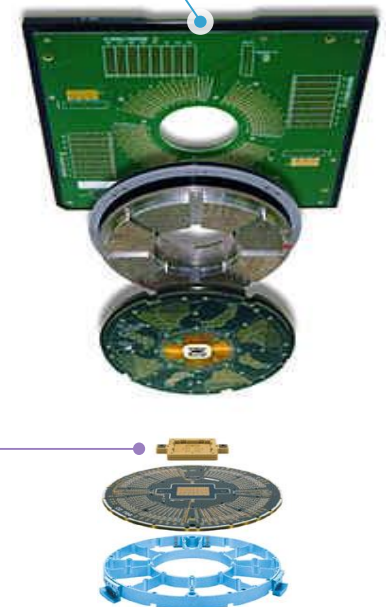
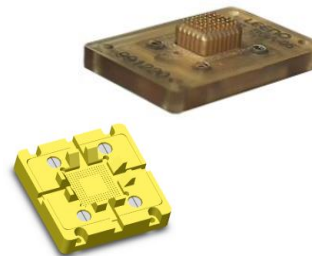
IC TEST SOCKET(with probe card)



### BGA Semiconductor



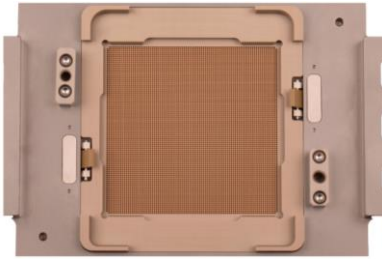
### IC TEST SOCKET



# IC TEST SOCKET

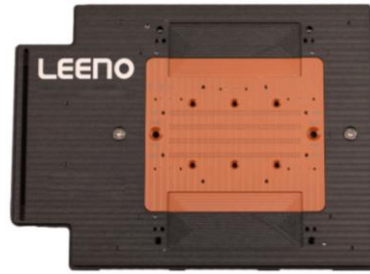
## System Level Test Socket

Proven capability in providing large volume custom-designed System Level Test Sockets for various device types & applications to meet the increasing demand for System Level Testing.



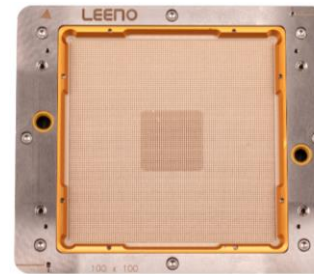
## RF Device Test Socket (Coaxial Socket)

With unparalleled technology, coaxial structure, and high-precision machining equipment, LEENO can provide RF test socket with high bandwidth, impedance matching and high frequency up to 100GHz.



## Large Device Test Socket

Proven Capability in providing general/coaxial testing solutions for large-size devices through FEM Simulation(structural deformation/Stress) & RF Simulation(112Gbps/224Gbps).



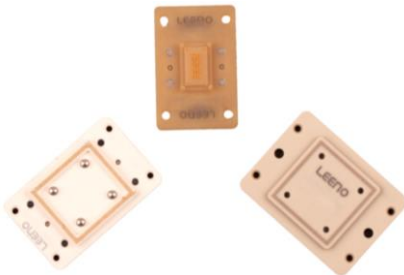
## High Power Cooling Lid

LEENO can provide effective cooling lid solutions based on thermal simulations to validate heat dissipation efficiency. LEENO has accumulated knowledge on thermodynamics and vast experience in actual testing.



## Memory Device Test Socket

With advanced precision injection molding equipment & patented technologies, LEENO can provide various test sockets for all kinds of memory devices.



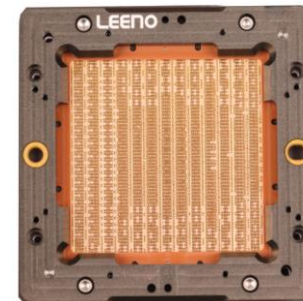
## Elastomer Socket

LEENO possesses its own design capabilities and manufacturing facilities, allowing us to create a unique structure of conductive particles embedded in silicone rubber.



## Strip Test Socket

LEENO can design and manufacture Multi-site Strip Test Socket which can accommodate various device types & testing requirements.



## Kelvin Socket

To meet the increasing requirement of accurate & stable voltage measurement, We have been supplying Full Kelvin or Mixed Kelvin Socket to many global customers.



# PROBE HEAD(CARD)

- ✓ The whole process semiconductor **inspection equipment to test electrical** characteristics in separated chips in wafer.
- ✓ LEENO is the **best leading technology company** to provide solution in competitive accelerating and evolved test market.

01

Long life Cycle

02

Quick Delivery

03

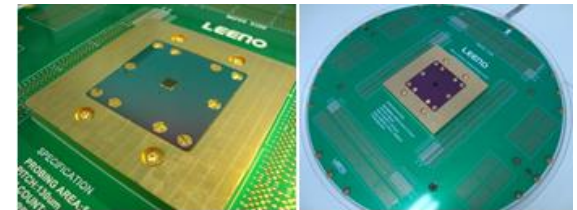
High Speed

04

Low Cost

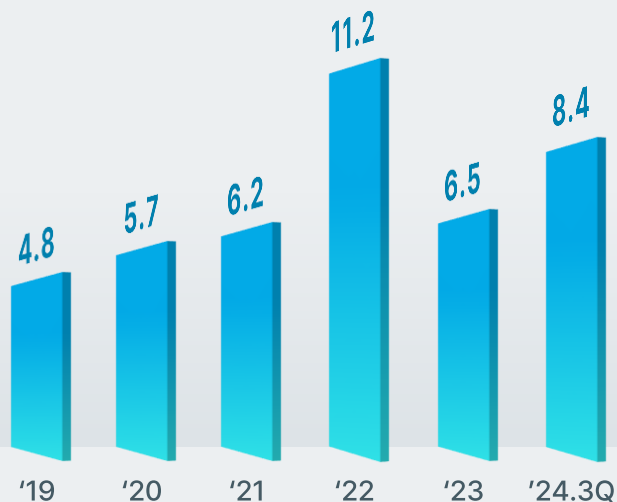
Semiconductor whole process (FAB)

Wafer level test (LEENO PROBE CARD)



## Sales amount

(UNIT : KRW bil)



## Wafer Level CSP/TSV Probe Card

150 $\mu$ m Pitch Flip Chip Quad Site Vertical Probe Card Total 13,500Pin

Specification	
Minimum Pitch	120 $\mu$ m
Planarity	$\leq 30\mu$ m
Probe Alignment	$\leq \pm 12\mu$ m
Scrub Mark	0~5 $\mu$ m
Tip Length	100 $\mu$ m~500 $\mu$ m $\pm 10\mu$ m Control
Temperature	-20 $^{\circ}$ C~120 $^{\circ}$ C
Probe Depth	6,900 $\mu$ m~12,000 $\mu$ m $\pm 200\mu$ m Control
Contact Resistance	$\leq 0.5\Omega$
Probe Tip Diameter	10 $\mu$ m~100 $\mu$ m Control
Pin Force	2.5g / Mil
Tip Material	Be-Cu(Au Plate) / Pd Alloy

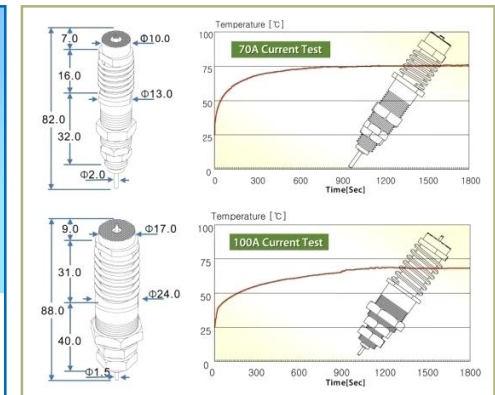
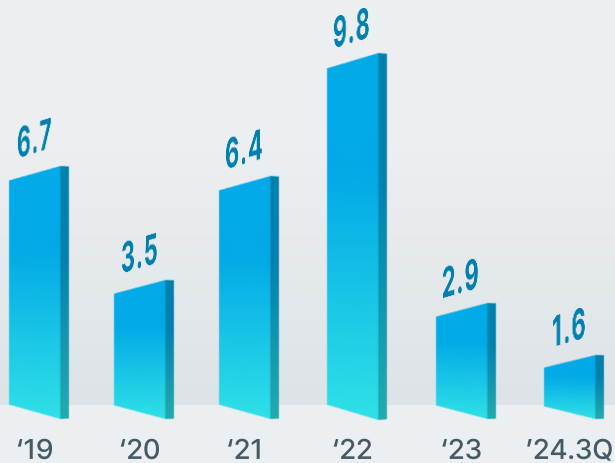
2012* 1Q	
Pin Count	20,000pin
Minimum Pitch	120 $\mu$ m

# Secondary Battery Test Pin

- ✓ The demand for **secondary batteries to be used for key items in the IT sector** such as portable products is expected to increase more compared with the previous year.
- ✓ LEENO manufacture high-current test pin for hybrid car to cope with active market.
- ✓ **World-class technology and pin production experience** in domestic market make possible for the final customer to use secondary battery safely.

## Sales amount

(UNIT : KRW bil)



# Ultrasonic wave probe component

- ✓ 25<sup>th</sup> Jan, 2010 LEENO Industrial Inc.

## makes an agreement about supplying Ultrasonic wave probe component with SIEMENS

- What is the 'Ultrasonic wave probe' ?

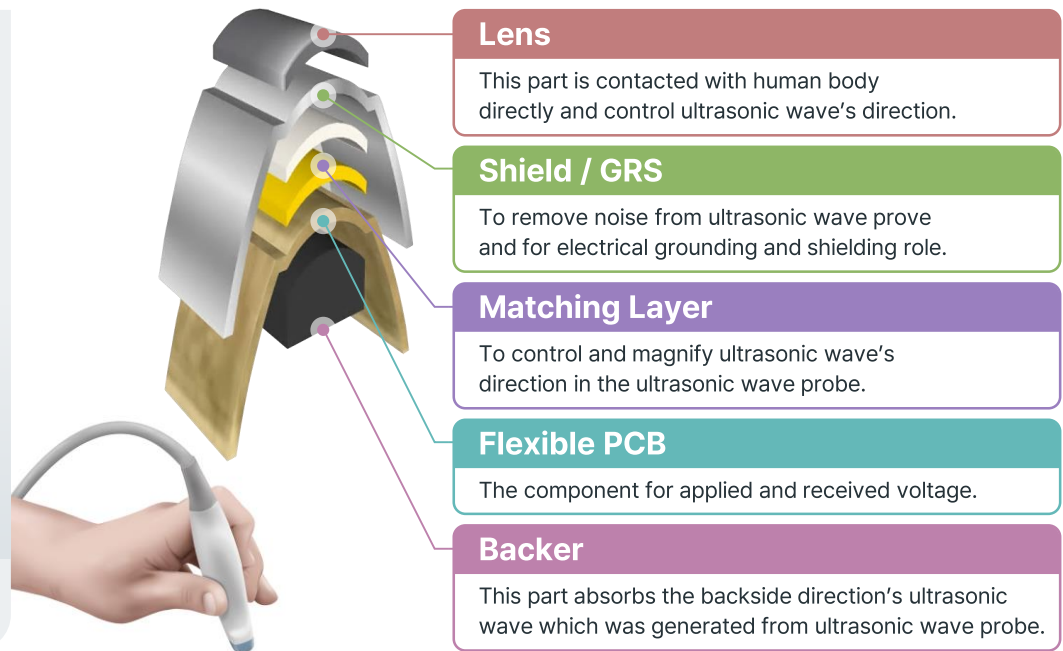
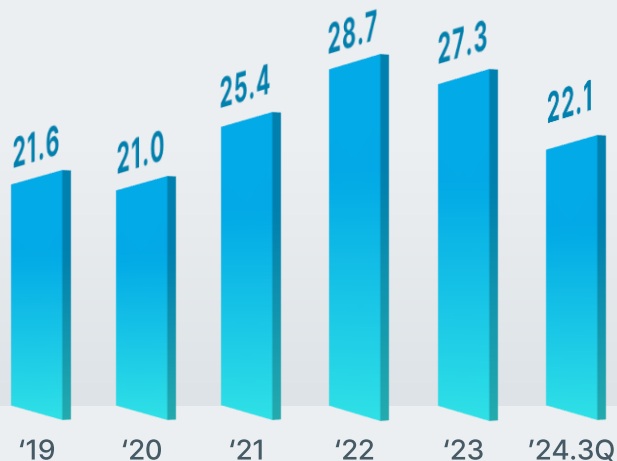
: It is single unit machine of ultrasonic diagnostic imaging device which has function to generate and detect ultrasonic wave and contacted directly with human body.

- ✓ This will be a base for **new growth** of LEENO's new market  
(\* Regarded as a consumable parts in ultrasonic wave diagnostic device)
- ✓ Manufacture the **core part of probe**, developing high value

## Sales amount

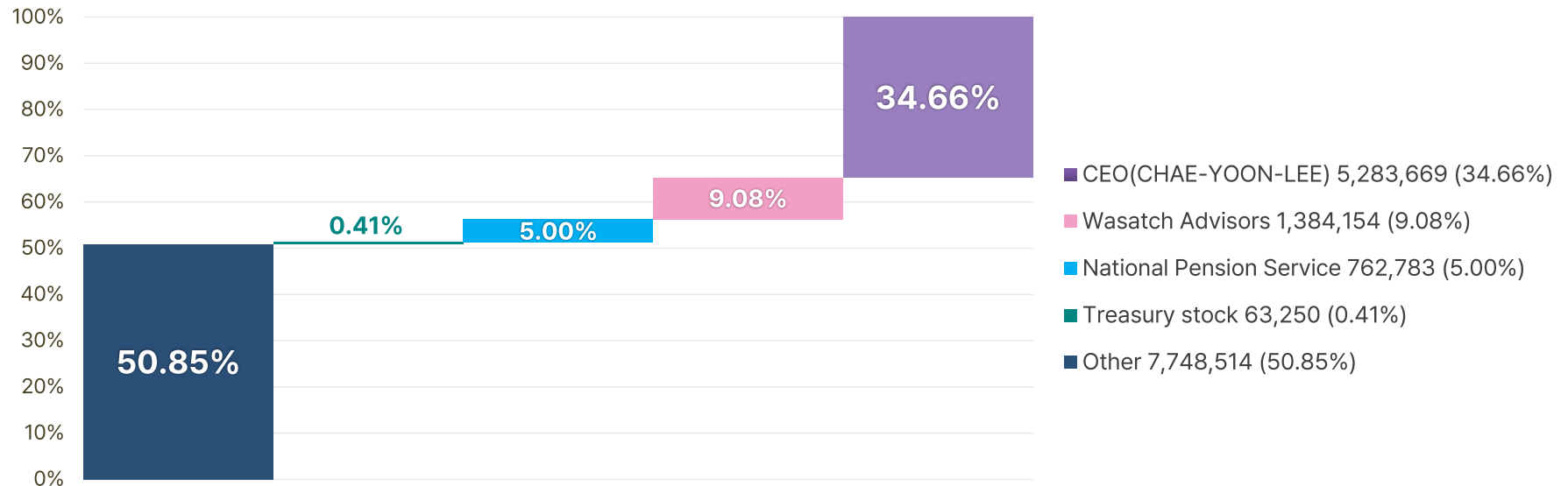
(UNIT : KRW bil)

\*Included sales of goods



# Stock Information

☑ LEENO is doing our **best to enhance the company's value** in return for your **trust and encouragement**.

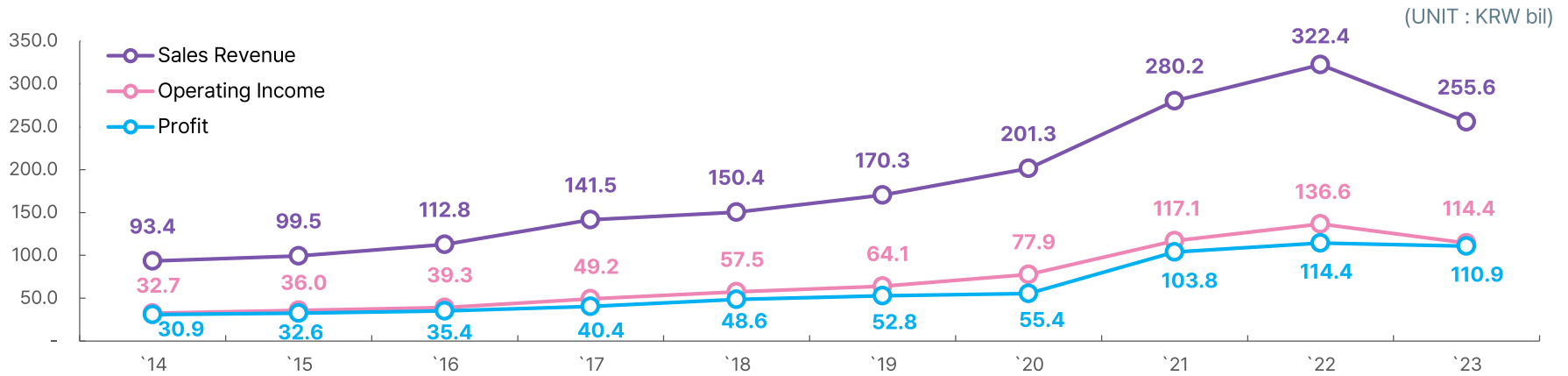


➤ Based on Stockholding status Report by National Pension Service(At JAN 3<sup>rd</sup>, 2025), Wasatch Advisors, Inc (At JUNE 17<sup>th</sup>, 2024)

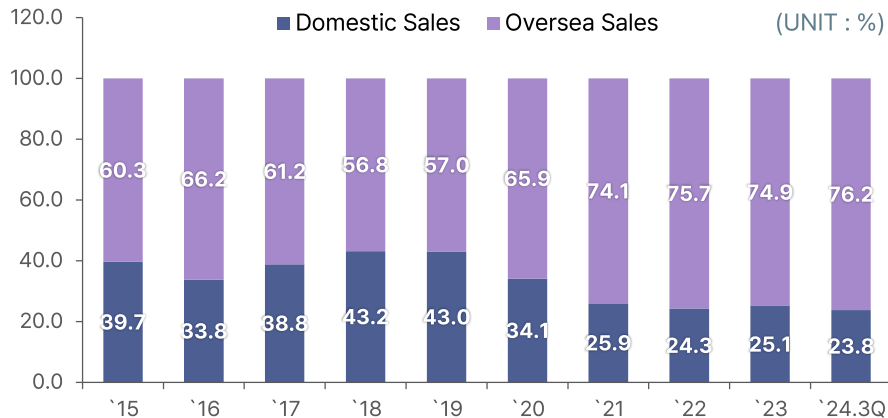
➤ According to Treasury stock, Please find the Disclosure of Treasury stock at NOV 29<sup>th</sup>, 2019.

# Year Performance

## » Year Performance

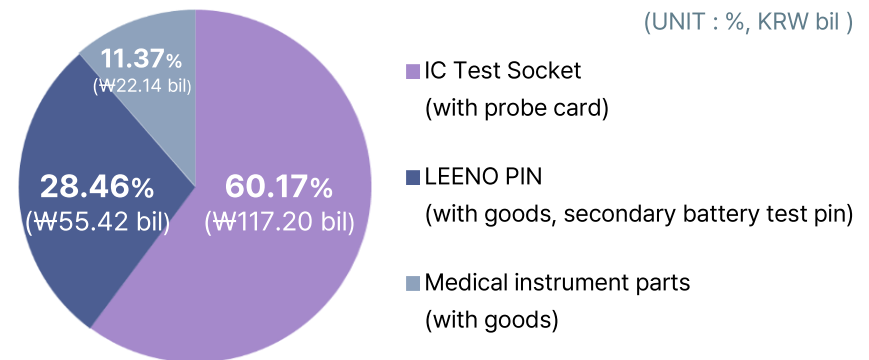


## » Export Ratio



## » Revenue Ratio

(Based on FY 2024.3Q Total Sales Revenue : 194.76 KRW bil)



# Dividend

## » Dividend

(UNIT : KRW)

Date	Par value	Net income	Earning Per Share (EPS)	Dividend	Dividend yield ratio(%)	Total Dividend amount
`23	500	110,923,015,440	7,308	3,000	1.48	45,537,360,000
`22	500	114,363,791,327	7,534	3,000	1.85	45,537,360,000
`21	500	103,805,815,149	6,839	2,500	1.26	37,947,800,000
`20	500	55,378,772,170	3,648	1,500	1.14	22,768,680,000
`19	500	52,790,182,377	3,485	1,200	1.87	18,214,944,000

▶ About the Dividend in 2019~2023, Total Dividend amount for 15,179,220 stocks except Treasury stocks(63,250).

### Stable Management

- Superior Financial structure and cashable property
- No-borrow Management & Maintenance
- Increasing of operating profit & Net income
- Maintenance of profit from high added value



### Policy for Stockholders



# Financial Statement

## » Balance Sheet

(UNIT : KRW)

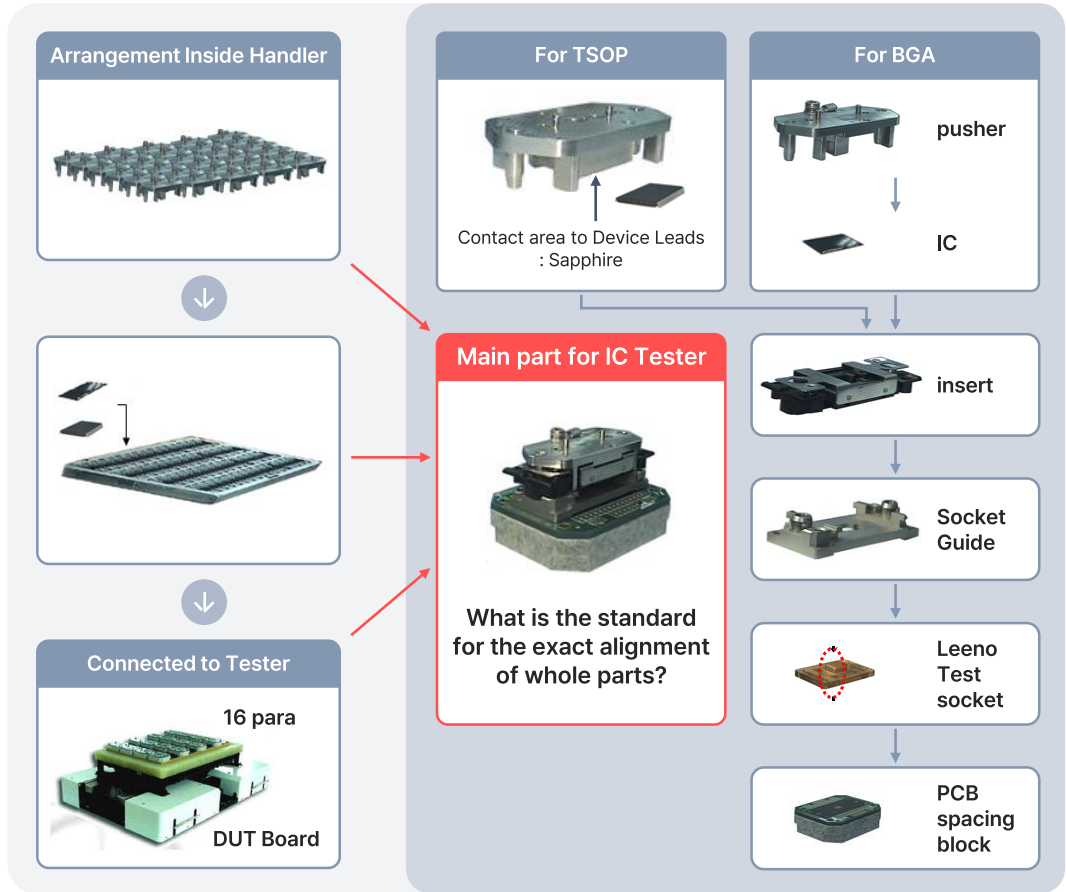
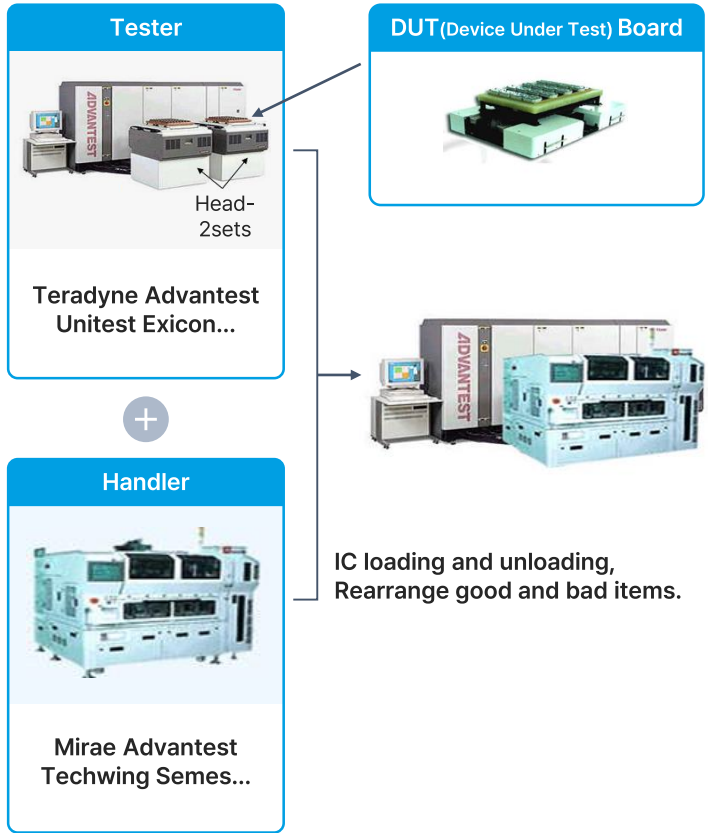
	FY 2024.3Q	FY 2023
I. Current Assets	412,543,270,639	372,372,898,847
II. Non-Current Assets	214,526,164,641	210,496,566,447
<b>Total Assets</b>	<b>627,069,435,280</b>	<b>582,869,465,294</b>
I. Current Liabilities	36,447,001,391	23,110,842,940
II. Non-current Liabilities	3,961,025,762	2,684,424,288
<b>Total Liabilities</b>	<b>40,408,027,153</b>	<b>25,795,267,228</b>
I. Issued capital	7,621,185,000	7,621,185,000
II. Capital Surplus	5,601,810,444	5,601,810,444
III. Other Capital Adjustments	(2,353,516,350)	(2,353,516,350)
IV. Retained Earnings	575,791,929,033	546,204,718,972
<b>Total Equities</b>	<b>586,661,408,127</b>	<b>557,074,198,066</b>
<b>Total Equities and Liabilities</b>	<b>627,069,435,280</b>	<b>582,869,465,294</b>

## » Statement of comprehensive income (Accumulated)

(UNIT : KRW)

	FY 2024.3Q	FY 2023.3Q	FY 2023
I. Revenue (Sales)	194,767,344,539	197,620,441,583	255,573,034,656
II. Cost of sales	97,724,587,300	102,256,106,274	127,238,409,519
<b>III. Gross Profit</b>	<b>97,042,757,239</b>	<b>95,364,335,309</b>	<b>128,334,625,137</b>
IV. Selling General Administrative Expenses	9,861,652,077	11,215,738,587	13,956,224,846
<b>V. Operating Income</b>	<b>87,181,105,162</b>	<b>84,148,596,722</b>	<b>114,378,400,291</b>
VI. Non-operating Income	10,188,478,940	24,013,490,117	27,865,067,804
<b>VII. Profit before tax</b>	<b>97,369,584,102</b>	<b>108,162,086,839</b>	<b>142,243,468,095</b>
VIII. Income tax expense	22,390,222,205	24,627,835,107	31,320,452,655
<b>IX. Profit</b>	<b>74,979,361,897</b>	<b>83,534,251,732</b>	<b>110,923,015,440</b>
X. Other comprehensive Income	145,208,164	157,366,570	(1,495,040,200)
<b>XI. Total comprehensive Income</b>	<b>75,124,570,061</b>	<b>83,691,618,302</b>	<b>109,427,975,240</b>
<b>XII. Basic Earnings per share</b>	<b>4,940</b>	<b>5,503</b>	<b>7,308</b>

# Appendix





**THANK YOU**

**LEENO**  
LEENO IND. INC.